

R0028588 R0628588

1U FANLESS 19" ,AC-DC REDUNDANT SERVER WITH INTEL® I7-9700TE PROCESSOR, RICH I/O INTERFACE, REDUNDANT AC-DC POWER SUPPLY , OPERATING TEMP. -20 ~ 60°C



- INTEL® COFFEE LAKE-REFRESH I7-9700TE (8 CORES, 3.8GHZ)
- 2 x SO-DIMM DDR4 2400/2666 MHZ UP TO 64GB
- 1 x PCIe x16 SLOT
- 1 x M.2(KEY M, PCIe x4 AND SATA3)EXPANSION SLOT
- 4 x USB3.1, 3 x DISPLAYPORT, 2 x LAN, 1 x LINE-OUT/MIC
- 2 x 2.5" SATA HDD/ SSD EASY SWAP TRAY
- 2 x 200W AC-DC POWER SUPPLY WITH REDUNDANT SUPPORT
- WIDE RANGE 90~260V AC-IN
- EXTENDED OPERATING TEMPERATURE -20 TO 60°C

Extended
Temperature
+60°C
-20°C



SPECIFICATIONS

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High Performance Processor	Socket LGA 1151 for Intel® Core i7/i5/i3/Celeron® (Supports up to 65W) Intel® Core™ i7-9700TE (8C x 3.8 GHz), 12MB Cache
Memory	2 x SO-DIMM DDR4 2400/2666 MHz up to 64GB
Chipset	Intel® Q370 Chipset
Expansion Slot	1 x PCIe x16 (Graphics card dimension should not be large than 170x110mm) 1x M.2 (Key M, 2242/2260/2280) with PCIe x4 and SATA3
DISPLAY	
Display Port	Resolution up to 4096 x 2304 60@Hz
STORAGE	
HDD/SDD	2 x 2.5" SATA HDD/SSD easy swap tray
ETHERNET	
Ethernet	Intel® I210 & I219LM GbE LAN (support 10/100/1000 Mbps for x2 RJ45 ports)
REAR I/O	
DisplayPort	3 x DP, resolution up to 4096 x 2304
Ethernet	2 x RJ45 Intel® I210 & I219LM GbE LAN (support 10/100/1000 Mbps)
Audio	2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out)
COM	1 x RS232/422/485
USB Port	4 x USB 3.1(10Gb/s)
AC-IN	1 x AC Inlet
FRONT I/O	
Button	1 x Power Button w/Indicator LED
Indicator LED	HDD
USB	2 x USB 2.0
Easy Swap SSD Tray	2
POWER REQUIREMENT	
Power Input	90~260V AC-in
APPLICATIONS, OPERATING SYSTEM	
Applications	Commercial and Industrial Platforms, Embedded Computing, Process Control, Intelligent Automation and manufacturing applications
Operating System	Windows 10 64Bit Ubuntu13.04, Ubuntu13.10, Ubuntu14.04, Fedora
PHYSICAL	
Dimension (W x D x H)	440 x430 x 44 mm
Weight	8.92Kg
Chassis	SECC
Heatsink	Aluminum Alloy, Corrosion Resistant
Finish	Anodic aluminum oxide

ENVIRONMENTAL	
MIL-STD-810G Test	Method 507.5, Procedure II (Temperature & Humidity) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I
EMC	(Temperature shock) CE and FCC compliance
Green Product	RoHS compliance
Operating Temp.	w/o Graphic Card (ET: -20 to 60°C; UT: -30 to 70°C) ;w/Graphic Card (0 to 50°C)
Storage Temp.	-40 to 85°C
Relative Humidity	5% to 95%, non-condensing

**ORDERING
INFORMATION**

ROC285BB-ET

19" 1U Rack-mount Rugged Fanless System with Intel® Coffelake Core i7-9700TE, Intel® UHD Graphics 630 with 3 DisplayPort, 1 x PCIe x16, 1 x M.2, 90~260V AC-in, Operating Temp. -20~+60°C

ROC285BB-UT

19" 1U Rack-mount Rugged Fanless System with Intel® Coffelake Core i7-9700TE, Intel® UHD Graphics 630 with 3 DisplayPort, 1 x PCIe x16, 1 x M.2, 90~260V AC-in, Operating Temp. -30~+70°C